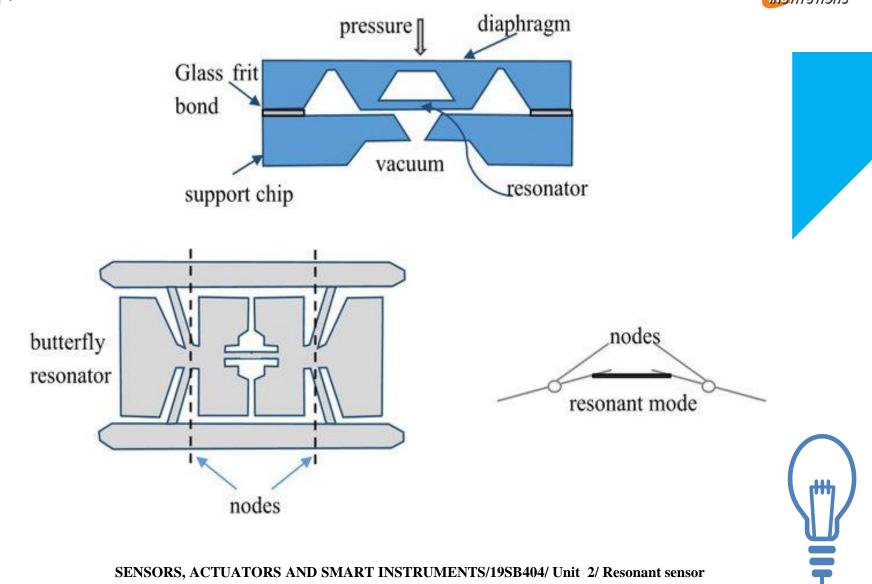


RESONANT SENSOR









Resonant sensors, which change their output frequency as a function of the quantity to be measured, are **attractive because of their high sensitivity, high resolution, and semi-digital output**.

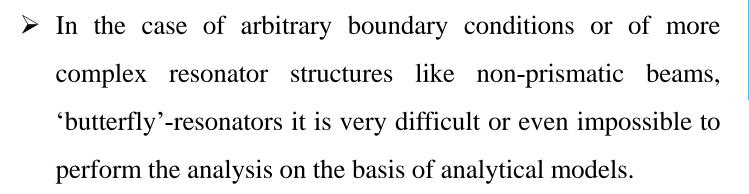
- They are based on the fact that the frequency of acoustic waves in solids is a highly sensitive probe for parameters that alter the geometry or the boundary conditions of the resonating structure.
- They are fabricated from single-crystal silicon using micromachining technologies like anisotropic wet etching and thin film deposition.





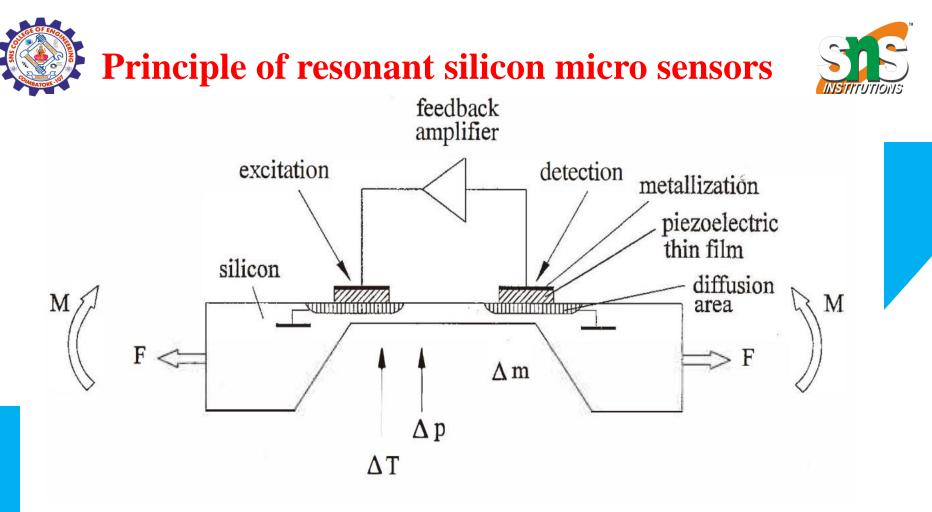
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For ideal boundary conditions the dynamic behaviour of simple resonator structures, for example double-clamped prismatic beams or all-around clamped flat diaphragms, may be modelled analytically with sufficient accuracy.



Instead numerical methods like the finite element method (FEM) may be used to study the behaviour of such resonators and to enable an efficient sensor design.





finite element method (FEM)





- The general scheme of a resonant pressure or force microsensor, which is **driven to resonant vibrations by piezoelectrical thin films,** is shown in Fig. 1.
- The resonant element consists of a silicon diaphragm or
 beam wet etched from the backside of the wafer.
 Piezoelectric thin films,
- for example zinc oxide (ZnO) layers are used to excite and to
 detect the vibrations of the resonator which is connected to
 the feedback loop of an oscillator circuit.









- patterning and doping of the ground electrode areas. In order to achieve a high electromechanical coupling efficiency, ZnO has to be grown with its c-axis perpendicular to the film plane and the silicon substrate.
- Well-oriented ZnO films may be deposited by r. f. sputtering from a Zn or ZnO target in an Ar/O2 plasma.
- The ZnO is wet etched in a stirred solution of HAc, H3PO4, and H2O in order to form the piezoelectrically active regions.





A sputtered and patterned Al metallization layer is used as the top electrode contact for the ZnO film.



After completing the planar front-side process, anisotropic wet etching from the rear is applied to produce the desired beam or diaphragm thickness. In the case of beamlike resonators, in the final step deep trenching is performed by plasma etching the diaphragm from the front side.







FUNCTION:



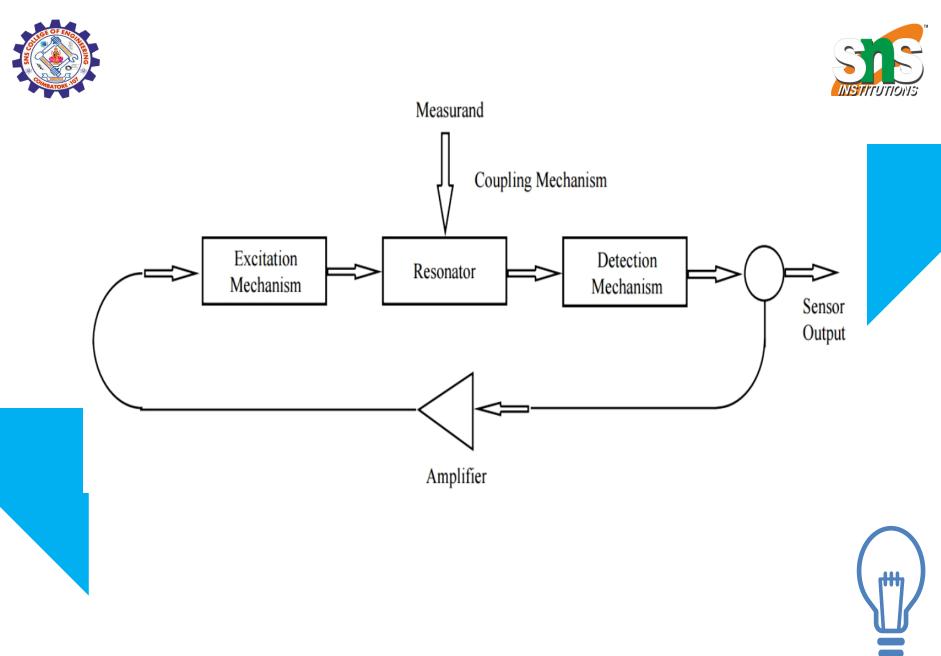
Mechanical loading of the resonator due to a pressure difference Δp at the diaphragm or due to external forces F and moments M exerted on the beam results in a tensile stress in the resonator element.

Stress stiffening effects will occur, which increase the stiffness of the resonator, thus changing its resonance frequency.

Furthermore, a mass loading Δm or a temperature rise ΔT may lead to a frequency decrease.

The output of the electronic oscillator circuit is fed to a frequency counter recording the load-dependent signal. The resonant microsensors are based on this principle; they consist of the **passive resonator element (i.e. beam, membrane, etc.) and active elements for excitation and detection (electronics) of vibrations.**









Assuming homogeneous and isotropic material properties, the resonance frequencies, mode shapes, and load dependent frequency changes can be calculated with sufficient accuracy.

$$f_n(F) \approx f_n(0) \sqrt{1 + \gamma_n \frac{Fl^2}{12E'I}},$$
(2)

where

$$f_n(0) = \frac{k_n^2}{2\pi} \sqrt{\frac{E'I}{\rho A l^4}}$$
(3)

and $f_n(0) = f_n(F = 0)$. The coefficients k_n and γ_n can be determined from the boundary conditions. For $n \ge 3$ they are approximately given by $k_n = \pi(n + 1/2)$ and $\gamma_n = 12(k_n - 2)/k_n^3$, and for n = 1,2 we have $k_1 = 4.730$, $k_2 = 7.853$, $\gamma_1 = 0.295$, and $\gamma_2 = 0.145$.







